PRODUCT FEATURES

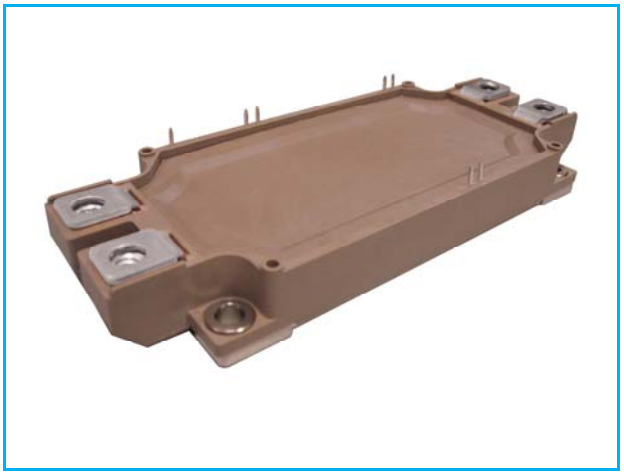
☐ IGBT^3 CHIP(Trench+Field Stop technology)

☐ Low saturation voltage and positive temperature coefficient

☐ Fast switching and short tail current

☐ Free wheeling diodes with fast and soft reverse recovery

☐ Temperature sense included



APPLICATIONS

☐ AC motor control

☐ Motion/servo control

☐ Inverter and power supplies

☐ Photovoltaic/Fuel cell

IGBT-inverter

ABSOLUTE MAXIMUM RATINGS(T_C *=25°C unless otherwise specified)*

Symbol	Parameter/Test Conditions		Values	Unit
V_{CES}	Collector Emitter Voltage	T_J=25℃	1200	V
V_{GES}	Gate Emitter Voltage		±20	
I_C	DC Collector Current	T_C=25℃, T_{Jmax}=150℃	325	A
		T_C=80℃, T_{Jmax}=150℃	225	
I_{CM}	Repetitive Peak Collector Current	tp=1ms	450	
P_{tot}	Power Dissipation Per IGBT	T_C=25℃, T_{Jmax}=150℃	1050	W

Diode-inverter

ABSOLUTE MAXIMUM RATINGS (T_C *=25°C unless otherwise specified)*

Symbol	Parameter/Test Conditions		Values	Unit
V_{RRM}	Repetitive Reverse Voltage	T_J=25℃	1200	V
$I_{F(AV)}$	Average Forward Current		225	A
I_{FRM}	Repetitive Peak Forward Current	tp=1ms	450	
I^2t		T_J=125℃, t=10ms, V_R=0V	9.1	KA^2S

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IGBT-inverter

ELECTRICAL CHARACTERISTICS *(T_C=25°C unless otherwise specified)*

Symbol	Parameter/Test Conditions			Min.	Typ.	Max.	Unit
$V_{GE(th)}$	Gate Emitter Threshold Voltage	$V_{CE}=V_{GE}$, I_C=9mA		5.0	5.8	6.5	V
$V_{CE(sat)}$	Collector Emitter Saturation Voltage	I_C=225A, V_{GE}=15V, T_J=25℃			1.7	2.15	V
		I_C=225A, V_{GE}=15V, T_J=125℃			2.0		
I_{CES}	Collector Leakage Current	V_{CE}=1200V, V_{GE}=0V, T_J=25℃				1	mA
		V_{CE}=1200V, V_{GE}=0V, T_J=125℃				5	mA
I_{GES}	Gate Leakage Current	V_{CE}=0V,V_{GE}=±15V, T_J=25℃		-400		400	nA
R_{gint}	Integrated Gate Resistor				3.3		Ω
Q_g	Gate Charge	V_{CE}=600V, I_C=225A , V_{GE}=±15V			2.1		μC
C_{ies}	Input Capacitance	V_{CE}=25V, V_{GE}=0V, f =1MHz			16		nF
C_{res}	Reverse Transfer Capacitance				0.75		nF
$t_{d(on)}$	Turn on Delay Time	V_{CC}=600V,I_C=225A R_G =3.3Ω, V_{GE}=±15V, Inductive Load	T_J=25℃		160		ns
			T_J=125℃		170		ns
t_r	Rise Time		T_J=25℃		45		ns
			T_J=125℃		50		ns
$t_{d(off)}$	Turn off Delay Time	V_{CC}=600V,I_C=225A R_G =3.3Ω, V_{GE}=±15V, Inductive Load	T_J=25℃		460		ns
			T_J=125℃		530		ns
t_f	Fall Time		T_J=25℃		100		ns
			T_J=125℃		150		ns
E_{on}	Turn on Energy	V_{CC}=600V,I_C=225A R_G =3.3Ω, V_{GE}=±15V, Inductive Load	T_J=25℃		9		mJ
			T_J=125℃		13.5		mJ
E_{off}	Turn off Energy		T_J=25℃		22.5		mJ
			T_J=125℃		33		mJ
I_{SC}	Short Circuit Current	tpsc≤10μS , V_{GE}=15V T_J=125℃,V_{CC}=900V			900		A
R_{thJC}	Junction to Case Thermal Resistance （Per IGBT）					0.12	K /W

Diode-inverter

ELECTRICAL CHARACTERISTICS *(T_C=25°C unless otherwise specified)*

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit
V_F	Forward Voltage	I_F=225A , V_{GE}=0V, T_J=25℃		1.65	2.15	V
		I_F=225A , V_{GE}=0V, T_J=125℃		1.65		
t_{rr}	Reverse Recovery Time	I_F=225A , V_R=600V dI_F/dt=-3600A/μs T_J =125℃		200		ns
I_{RRM}	Max. Reverse Recovery Current			180		A
E_{rec}	Reverse Recovery Energy			18		mJ
R_{thJCD}	Junction to Case Thermal Resistance （Per Diode）				0.2	K /W

NTC CHARACTERISTICS *(T_C=25°C unless otherwise specified)*

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit
R_{25}	Resistance	T_C =25℃		5		KΩ
$B_{25/50}$	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298.15\ K))]$			3375		K

MODULE CHARACTERISTICS *(T_C=25°C unless otherwise specified)*

Symbol	Parameter/Test Conditions		Values	Unit
T_{Jmax}	Max. Junction Temperature		150	℃
T_{Jop}	Operating Temperature		-40~125	
T_{stg}	Storage Temperature		-40~125	
V_{isol}	Isolation Breakdown Voltage	AC, 50Hz(R.M.S), t=1minute	3000	V
CTI	Comparative Tracking Index		＞225	
Torque	to heatsink	Recommended（M5）	2.5~5	Nm
	to terminal	Recommended（M6）	3~5	Nm
Weight			350	g

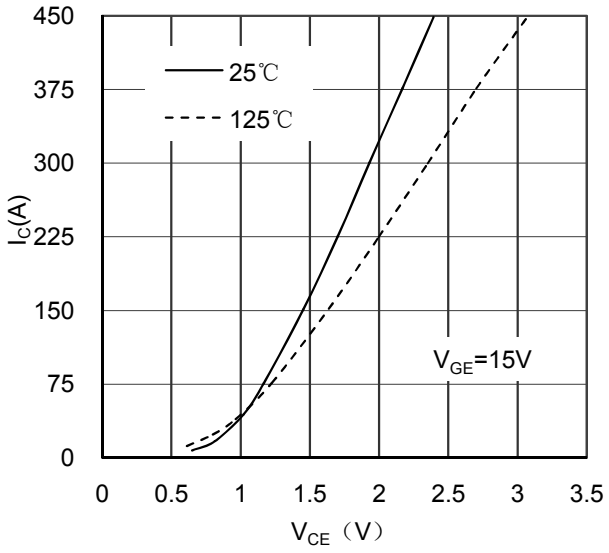


Figure 1. Typical Output Characteristics IGBT-inverter

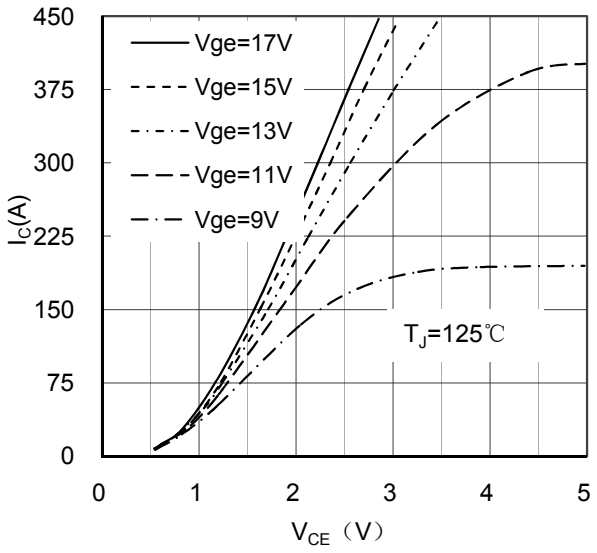


Figure 2. Typical Output Characteristics IGBT-inverter

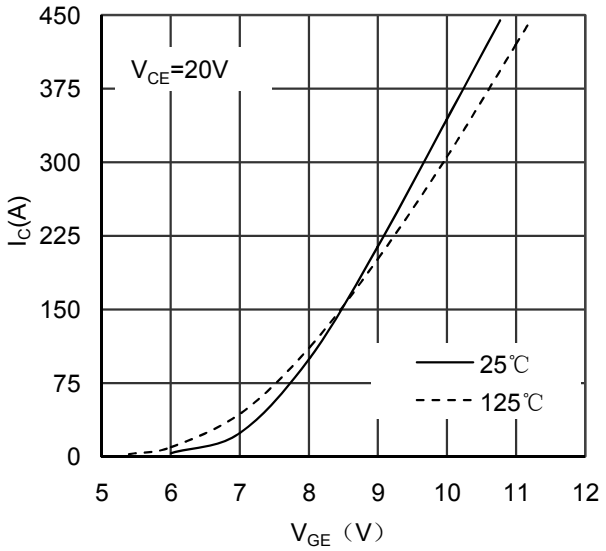


Figure 3. Typical Transfer characteristics IGBT-inverter

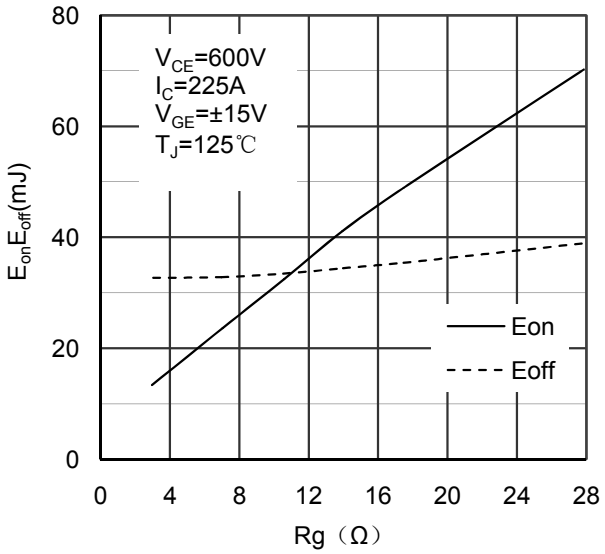


Figure 4. Switching Energy vs Gate Resistor IGBT-inverter

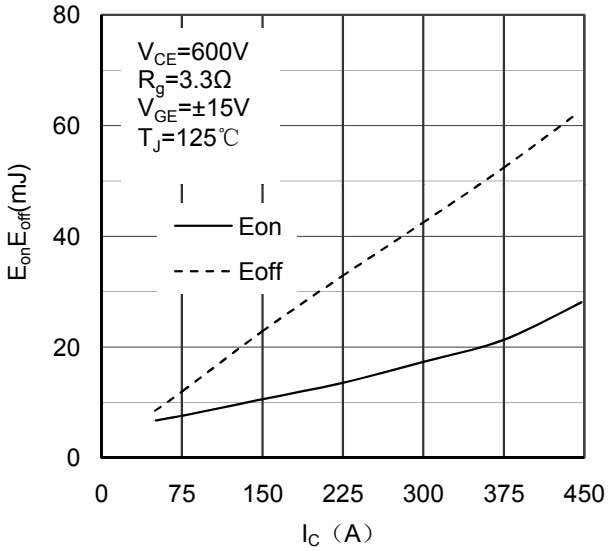


Figure 5. Switching Energy vs Collector Current IGBT-inverter

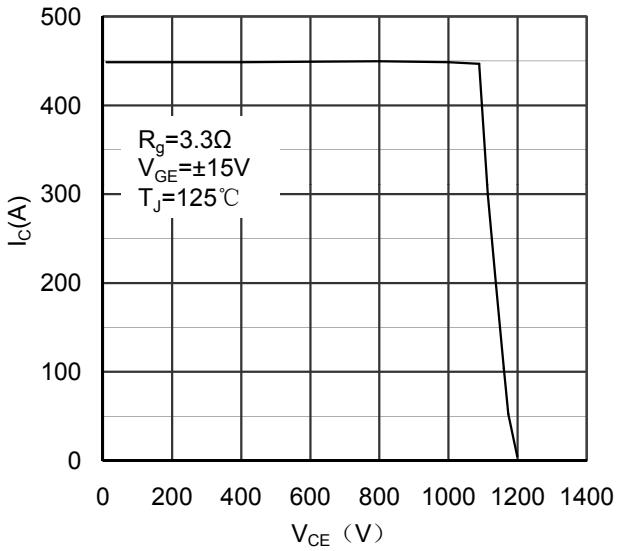


Figure 6. Reverse Biased Safe Operating Area IGBT-inverter

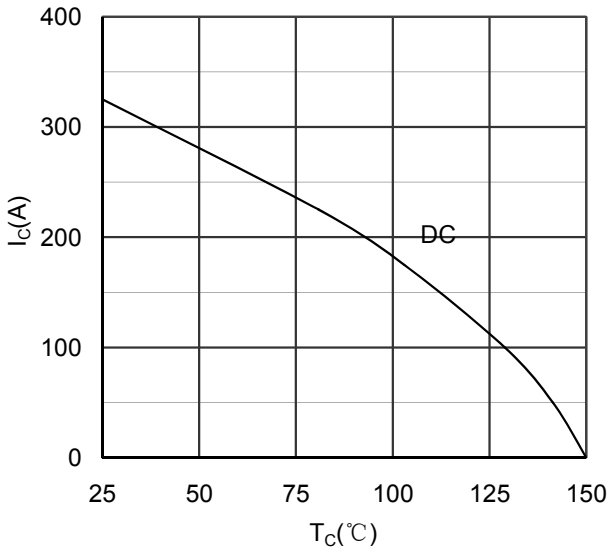


Figure 7. Collector Current vs Case temperature IGBT -inverter

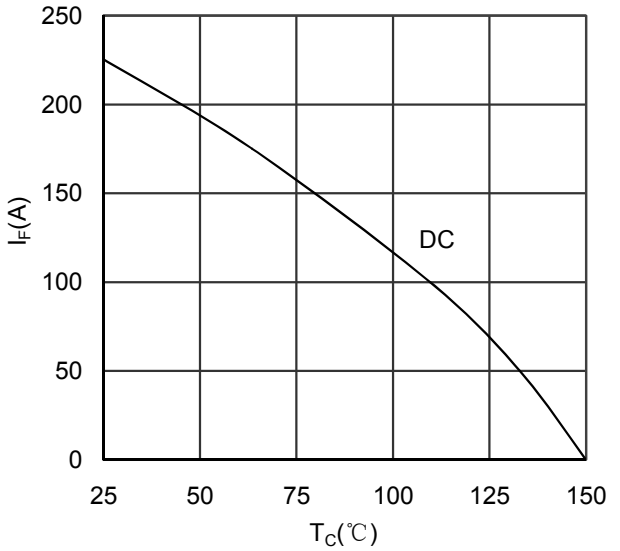


Figure 8. Forward current vs Case temperature Diode -inverter

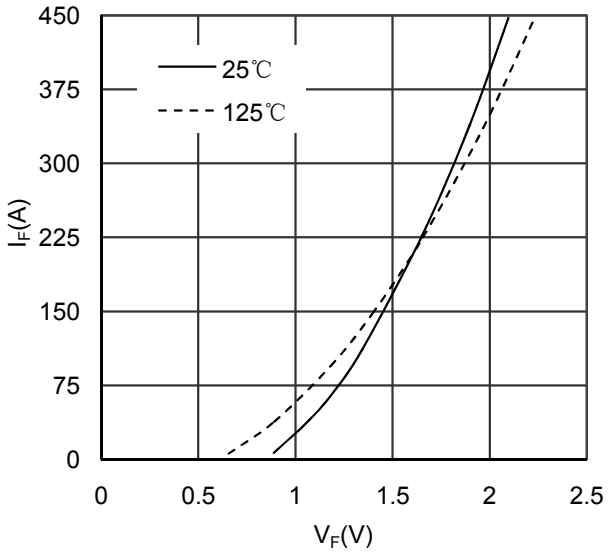


Figure 9. Diode Forward Characteristics Diode -inverter

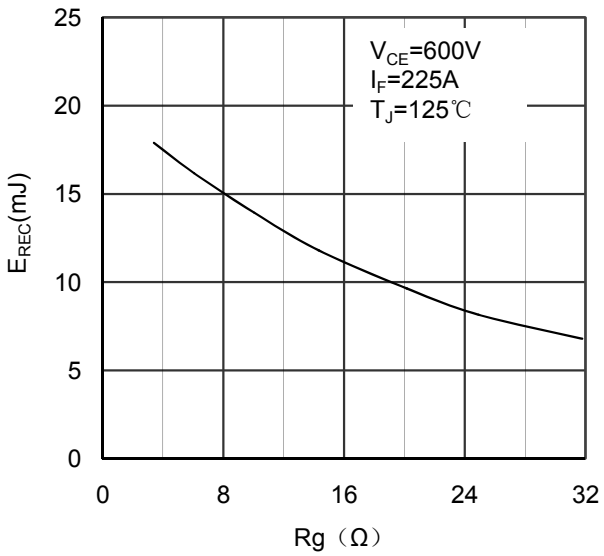


Figure 10. Switching Energy vs Gate Resistor Diode - inverter

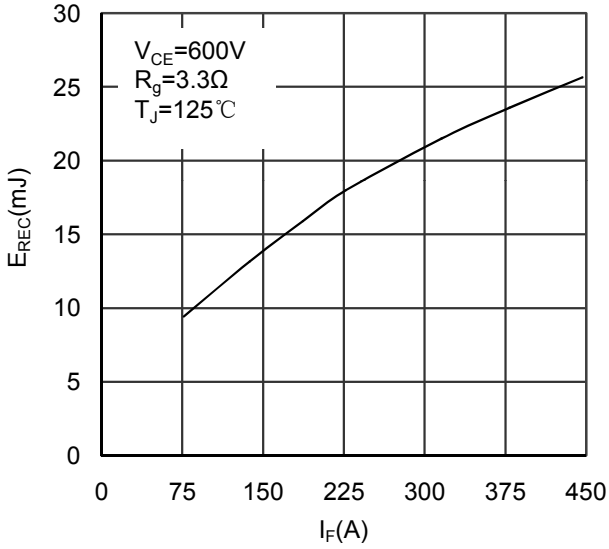


Figure 11. Switching Energy vs Forward Current Diode-inverter

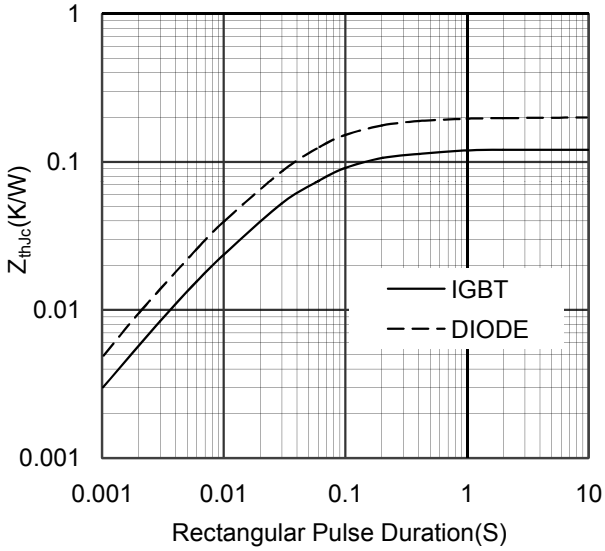


Figure 12. Transient Thermal Impedance of Diode and IGBT-inverter

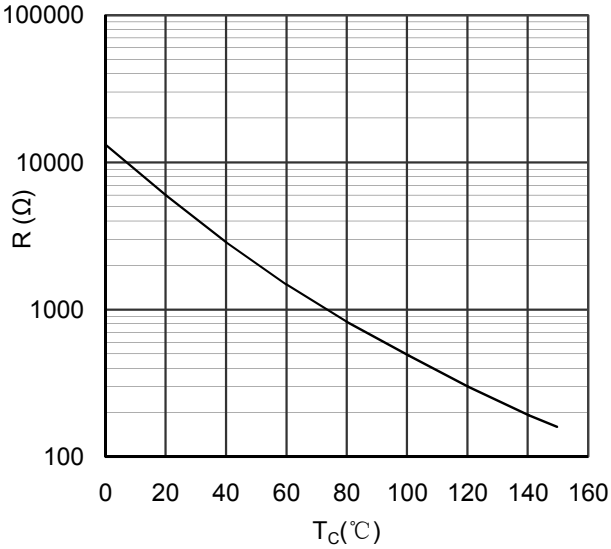


Figure 13. NTC Characteristics

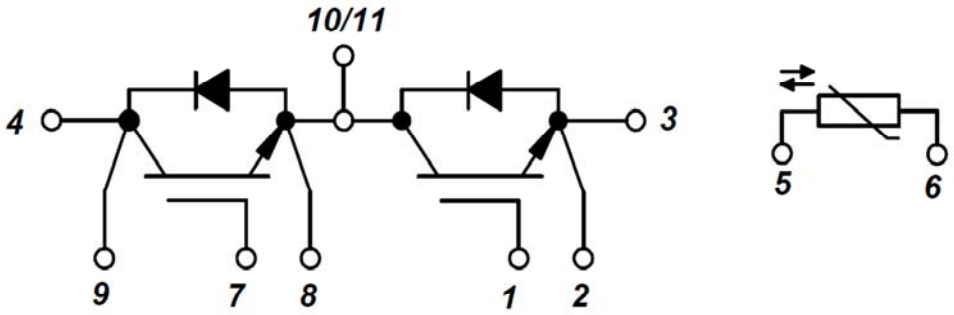
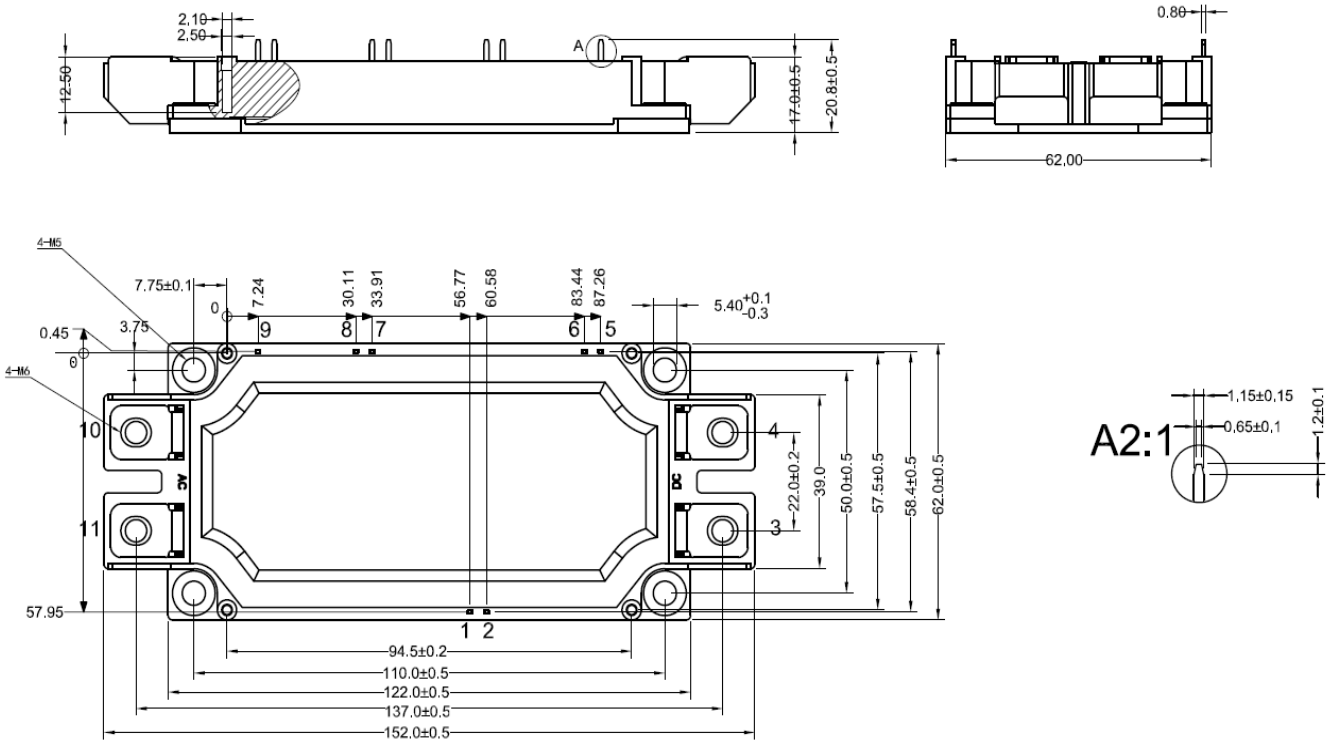


Figure 14. Circuit Diagram



Dimensions in (mm)

Figure 15. Package Outline